

35 U.S.C. §121 Restriction and Election of Claims 1-14 and 23-27

The Examiner has deemed claims 1-14 and 23-27 to be drawn to one invention (invention I) and claims 15-22 to be drawn to another invention (invention II). The Examiner has communicated to Applicant a requirement to restrict the present application to a single invention under 35 U.S.C. §121. Applicant hereby provisionally elects to prosecute claims 1-14 and 23-27 of invention I.

As a result of the aforescribed election, claims 15-22 are withdrawn from further consideration by the Examiner, since they have been deemed to be drawn to a non-elected invention. Applicant may pursue such claims in a separate application.

Amendments Made to Claims 2-12 and 24-27

Amendments have been made to claims 2-12 and 24-27 by Applicant to correct minor typographical errors, only.

Condition for Allowance

Applicant submits that all rejections and objections have been overcome and the present application is now in condition for allowance. If there are any additional charges or shortages related to the present communication, please charge our Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP



Dated: August 2, 2002

Mark V. Seeley  
Registration No. 32,299

**CERTIFICATE OF TRANSMISSION**

37 C.F.R. § 1.8(a)

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office on August 2, 2002.

Name: Mark V. Seeley

Signature: 

VERSION WITH MARKINGS TO SHOW CHANGES MADE

2. (Amended) The [apparatus] package of claim 1, wherein the package is a ball grid array package.
3. (Amended) The [apparatus] package of claim 1, wherein the package is a pin grid array package.
4. (Amended) The [apparatus] package of claim 1, wherein the die is attached to the lid, and the lid serves to conduct heat away from the die.
5. (Amended) The [apparatus] package of claim 1, wherein a vent-hole is formed through the lid.
6. (Amended) The [apparatus] package of claim 1, wherein the pattern in which the sealant is disposed between the lid and the substrate is a substantially rectangular pattern with [the] at least one break.
7. (Amended) The [apparatus] package of claim 6, wherein the rectangular pattern has four breaks, one in each side of the substantially rectangular pattern.

8. (Amended) The [apparatus] package of claim 7, wherein the four breaks comprise a minimum 10% of the total length of what would otherwise be an unbroken substantially rectangular pattern.
9. (Amended) The [apparatus] package of claim 6, wherein the rectangular pattern has four breaks, one in each corner of the substantially rectangular pattern.
10. (Amended) The [apparatus] package of claim 9, wherein the four breaks comprise a minimum 10% of the total length of what would otherwise be an unbroken substantially rectangular pattern.
11. (Amended) The [apparatus] package of claim 1, wherein the substrate is susceptible to absorbing moisture, and the pressure existing between the substrate and the lid is as a result of moisture being released within the package by the substrate and being converted to steam.
12. (Amended) The [apparatus] package of claim 11, wherein the substrate is comprised of organic material.

24. (Amended) The [apparatus] electronic device of claim 23, wherein the die is attached to the lid, and the lid serves to conduct heat away from the die.

25. (Amended) The [apparatus] electronic device of claim 23, wherein the pattern in which the sealant is disposed between the lid and the substrate is a substantially rectangular pattern with [the] at least one break.

26. (Amended) The [apparatus] electronic device of claim 25, wherein the rectangular pattern has four breaks, one in each side of the substantially rectangular pattern.

27. (Amended) The [method] electronic device of claim 23, wherein the die is attached to the substrate using a controlled collapsed chip connection.